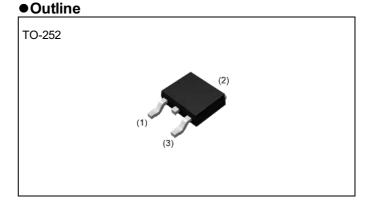
#### Nch 190V 10A Power MOSFET

V <sub>DSS</sub>	190V
R <sub>DS(on)</sub> (Max.)	182mΩ
I <sub>D</sub>	±10A
P <sub>D</sub>	85W

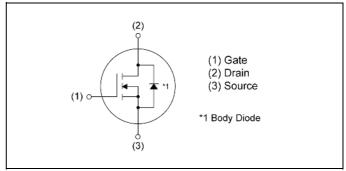
# \_ \_



#### Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free plating; RoHS compliant

## •Inner circuit



## Application

Switching Power Supply

## Packaging specifications

<u> </u>				
Packing	Embossed Tape			
Packing code	TL1			
Marking	RD3S100CN			
Quantity (pcs)	2500			

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	190	V
Continuous drain current (T <sub>c</sub> = 25°C)	I <sub>D</sub> *1	±10	А
Pulsed drain current	I <sub>DP</sub> *2	±40	А
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	5.0	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	8.33	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	85	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

#### ●Thermal resistance

Downwortow	Cymah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	1.46	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	147	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# • Electrical characteristics $(T_a = 25^{\circ}C)$

Darameter	Cumb of	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	190	-	-	V	
		V <sub>DS</sub> = 190V, V <sub>GS</sub> = 0V					
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	10	μA	
aram canoni		T <sub>j</sub> = 125°C	-	-	100		
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	0.5	-	2.5	V	
	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5A					
		$T_j = 25^{\circ}C$	-	130	182		
Static drain - source on - state resistance		T <sub>j</sub> = 125°C	-	195	-	mΩ	
		V <sub>GS</sub> = 4V, I <sub>D</sub> = 5A		126	100		
		T <sub>j</sub> = 25°C	-	136	190		
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	4.5	-	Ω	

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatar	Cymah al	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	UIIIL	
Forward Transfer Admittance	$ Y_{fs} ^{*4}$ $V_{DS} = 10V, I_D = 5.0A$		6	12	-	S	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2000	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	95	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	60	-		
Turn - on delay time	t <sub>d(on)</sub> *4	V <sub>DD</sub> ≈ 100V, V <sub>GS</sub> = 10V	-	15	-		
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 5A	-	20	-		
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 20\Omega$	-	140	-	ns	
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	75	-		

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Davamatar	Currelle e l	Conditions	Values			l limit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg*4	V <sub>DD</sub> ≈ 100V	-	52	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 10A	-	5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = 10V	-	11	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 100V, I <sub>D</sub> = 10A	-	2.5	-	V

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $\simeq$  500 $\mu$ H, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , starting T<sub>j</sub> = 25°C

<sup>\*4</sup> Pulsed

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I <sub>S</sub> *1			-	10	Α	
Pulsed source current	I <sub>SP</sub> *2	T <sub>C</sub> = 25°C	1	-	40	Α	
Source-Drain voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_{S} = 10A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *4		1	95	1	ns	
Reverse recovery charge	Q <sub>rr</sub> *4	$I_S = 5A$ di/dt = 100A/ $\mu$ s	-	255	-	nC	
Peak reverse recovery current	I <sub>rr</sub>		-	5.5	-	Α	

Fig.1 Power Dissipation Derating Curve

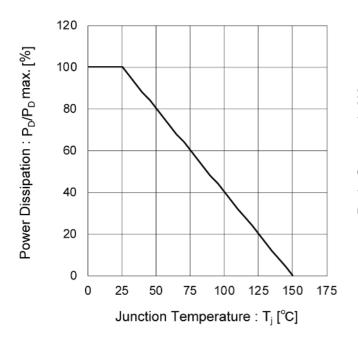


Fig.2 Maximum Safe Operating Area

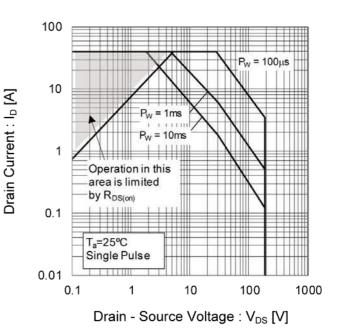
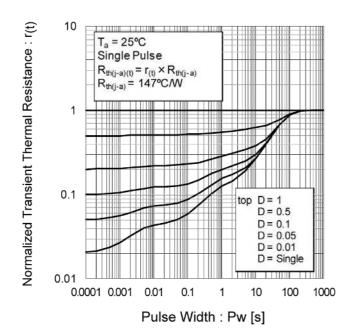


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Avalanche Current : IAS [A]

#### • Electrical characteristic curves

Fig.4 Avalanche Current vs. Inductive Load

 $V_{DD} = 50 \text{V}, R_{G} = 25 \Omega \\ V_{GF} = 10 \text{V}, V_{GR} = 0 \text{V} \\ \text{Starting T}_{ch} = 25 ^{\circ}\text{C}$  10 0.1 0.01 0.1 0.01 1 1 1 0.01 0.1 0.1 0.01 0.1 0.1 0.01 0.1 0.01 0.1 0.01 0.1 0.01 0.1 0.01 0.1 0.1 0.01 0.1 0.01 0.1 0.01 0.1 0.01 0.1 0.01 0.1 0.01 0.01 0.01 0.01 0.01 0.01

Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

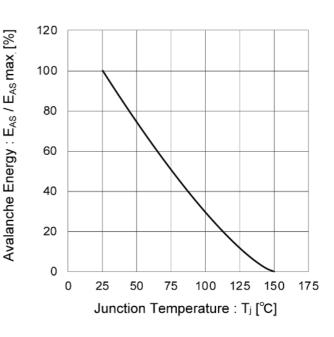


Fig.6 Typical Output Characteristics(I)

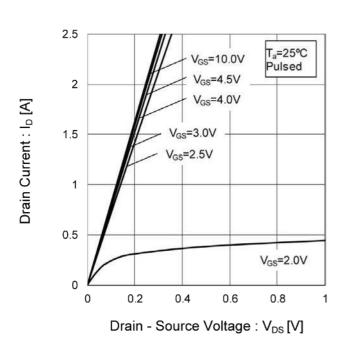
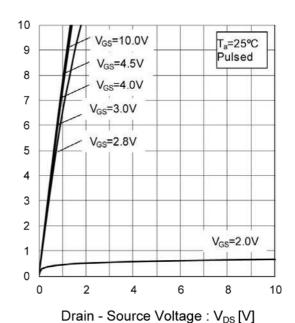


Fig.7 Typical Output Characteristics(II)



Drain Current: Ip [A]

Fig.8 Breakdown Voltage vs. Junction Temperature

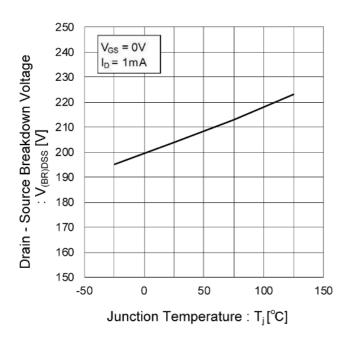


Fig.9 Typical Transfer Characteristics

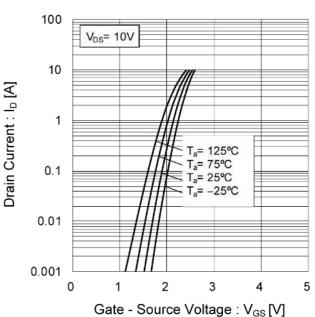


Fig.10 Gate Threshold Voltage vs. Junction Temperature

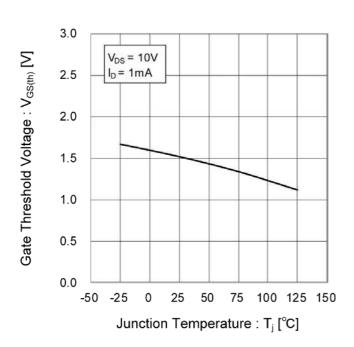


Fig.11 Transconductance vs. Drain Current

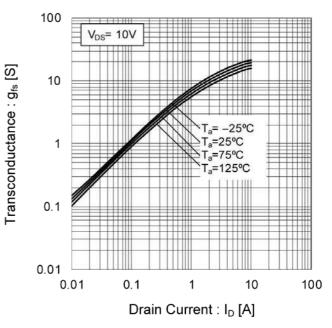


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

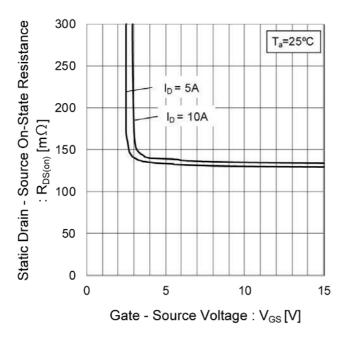


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current( I )

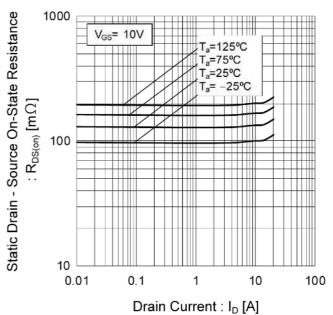


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current( II )

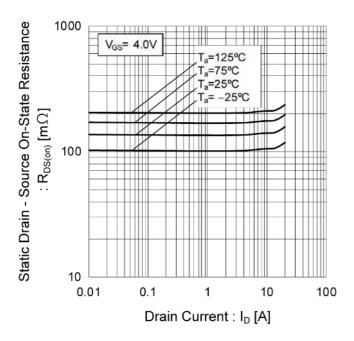


Fig.15 Static Drain - Source On - State Resistance vs. Junction Temperature

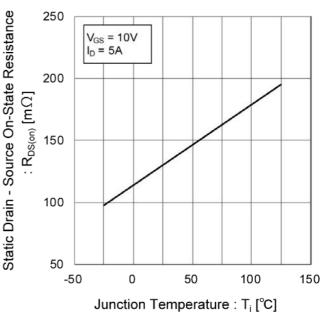


Fig.16 Source Current vs. Source-Drain Voltage

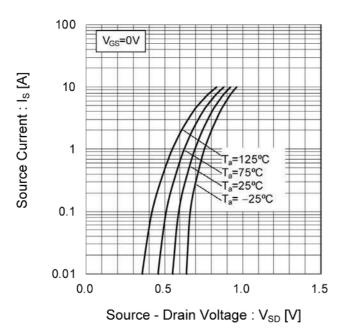
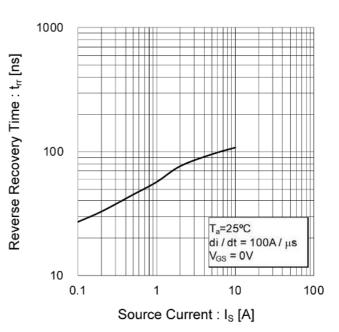


Fig.17 Source Current vs. Reverse Recovery Time



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ROHM

Fig.18 Typical Capacitance vs. Drain - Source Voltage

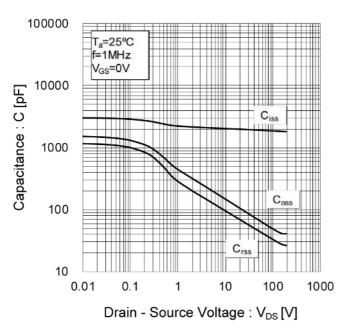


Fig.19 Switching Characteristics

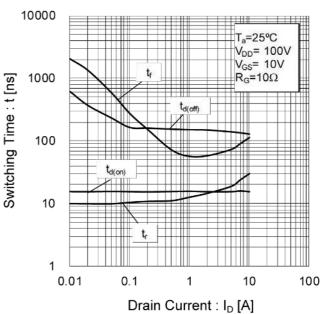
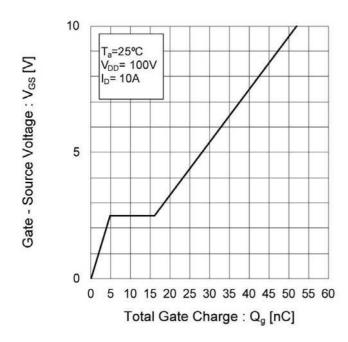


Fig.20 Dynamic Input Characteristics



#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

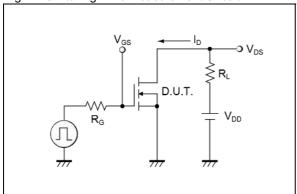


Fig.2-1 Gate Charge Measurement Circuit

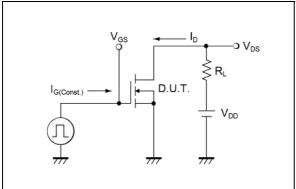


Fig.3-1 Avalanche Measurement Circuit

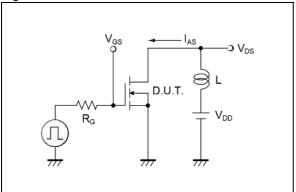


Fig.4-1 trr Measurement Circuit

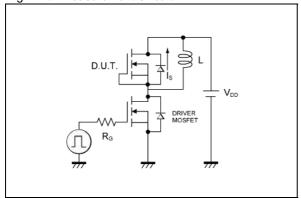


Fig.1-2 Switching Waveforms

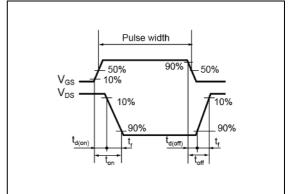


Fig.2-2 Gate Charge Waveform

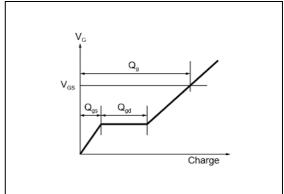


Fig.3-2 Avalanche Waveform

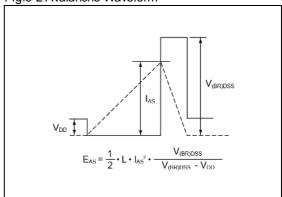
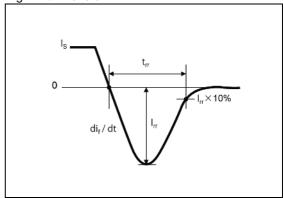
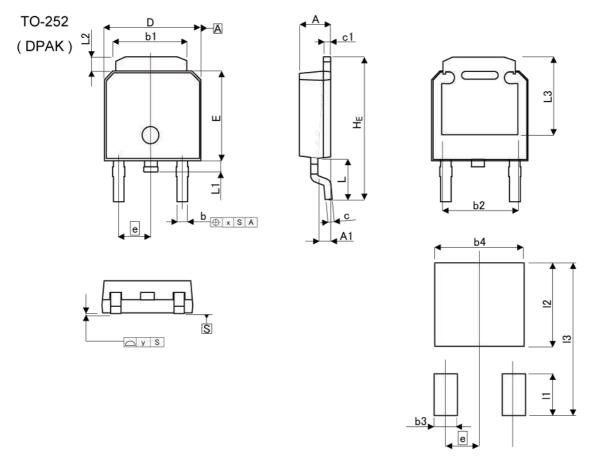


Fig.4-2 trr Waveform



#### Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	ETERS	INC	HES
DIIVI [	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	89
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.114	
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.209	
х	¥	0.25	\$ 150 miles	0.010
у	76	0.10	(F)	0.004
DIM -	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
b3		1.15	9 <b>4</b> 6	0.045
b4		5.55	0.50	0.219
11	¥	2.77	S(#2))	0.109
12	-	5.50	2 <b>5</b> %	0.217
13	81	10.40	RES	0.409

Dimension in mm/inches



# **Notice**

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Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	СГУССШ
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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